



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: **Yoshino, et al.**

Serial No.: **09/909,013**

Filed: **07/19/2001**

For: **Semiconductor Package Insulation Film and  
Manufacturing Method Thereof**

Docket No.: **TI-29448**

Examiner: **Geyer, Scott**

Art Unit: **2829**

Conf. No.: **8724**

TRANSMITTAL OF FORMAL DRAWINGS

Assistant Commissioner For Patents  
Attn: Official Drafts Person  
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8(a)

I hereby certify that the above correspondence is being deposited with  
the U.S. Postal Service as First Class Mail in an envelope addressed  
to: Assistant Commissioner For Patents, Washington, DC 20231.

  
Elizabeth Austin

10/3/2002  
Date

Dear Sir:

Submitted herewith are 8 sheets of formal drawings.

The enclosed drawings are being provided in a timely manner therefore no additional  
fee is necessary.

Respectfully submitted,



Michael K. Skrehot  
Attorney for Applicants  
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